CLAIMS

1. A polishing composition characterized by comprising a composition (A) and at least one selected from an organic acid and an organic salt, wherein

the composition (A) contains hydroxyethyl cellulose, ammonia, abrasive grains, and water, and

the electrical conductivity of the polishing composition is 1.2 to 8 times the electrical conductivity of the composition (A).

2. The polishing composition according to claim 1, further comprising a surfactant.

3. A method for polishing a substrate surface by using the polishing composition according to claim 1 or 2.

4. A method for manufacturing a substrate, comprising a step for polishing a substrate surface by using the method according to claim 3.

CLAIMS

1. A polishing composition characterized by comprising a composition (A), a surfactant, and at least one selected from an organic acid and an organic salt, wherein

the composition (A) contains hydroxyethyl cellulose, ammonia, abrasive grains, and water, and

the electrical conductivity of the polishing composition is 1.2 to 8 times the electrical conductivity of the composition (A).

2. A method for polishing a substrate surface by using the polishing composition according to claim 1.

3. A method for manufacturing a substrate, comprising a step for polishing a substrate surface by using the method according to claim 2.